

General Description

The SJD20N054 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a wide variety of applications.

Features

- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

Application

- PWM Applications
- Load Switch
- Power Management

D

Key Performance Parametes

Parameter	Value	Unit
V _{DS}	20	V
R _{DS(ON)_TYP}	4.3	mΩ
ID	64	А
Q _G	22	nC

RoHS



Schematic Diagram

TO-252(DPAK) top view

Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJD20N054	SJD20N054	TO-252	Таре	\	/	2500 Pcs

Table 1. Absolute Maximum Ratings (T_c=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage (V _{GS} =0V)	20	V
V _{GS}	Gate-Source Voltage (V _{DS} =0V)	±20	V
	Drain Current-Continuous(Tc=25°C)	64	A
Ι _D	Drain Current-Continuous(Tc=100℃)	40	A
IDM (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	256	A
Po	Maximum Power Dissipation(Tc=25°C)	33	W
PD	Maximum Power Dissipation(Tc=100°C)	13	W
Eas	Avalanche energy (Note 2)	90	mJ
TJ, TSTG	Operating Junction and Storage Temperature Range	-55 To 150	C

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		3.8	°C/W



Table 3. Electrical Characteristics (T_J=25 $^\circ\!\!\mathrm{C}$ unless otherwise noted)

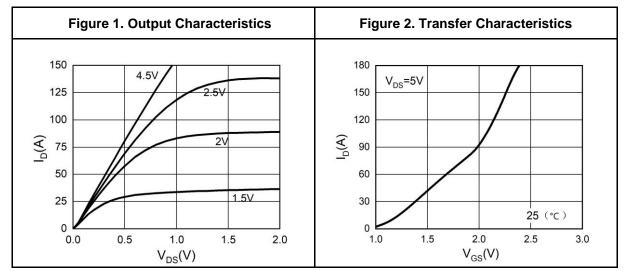
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States	-					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250µA	20			V
		V _{DS} =20V, V _{GS} =0V T _J =25℃			1	μA
IDSS	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V T _J =125℃			100	μA
lgss	Gate-Body Leakage Current	$V_{GS}=\pm 12V$, $V_{DS}=0V$			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA	0.4		1	V
g fs	Forward Transconductance	V _{DS} =5V, I _D =20A		82		S
Rds(on)	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =20A T _J =25℃		4.3	5.6	mΩ
Rds(on)	Drain-Source On-State Resistance	V _{GS} =2.5V, I _D =15A T _J =25℃		5.3	7	mΩ
Dynamic Chara	acteristics		L	•	L	
Ciss	Input Capacitance			1987		pF
Coss	Output Capacitance	V _{DS} =10V,V _{GS} =0V, f=1.0MHz		243		pF
Crss	Reverse Transfer Capacitance			224		pF
Rg	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		1.6		Ω
Switching Para	meters		L	•	L	
t _{d(on)}	Turn-on Delay Time			10		nS
tr	Turn-on Rise Time	V _{GS} =4.5V, V _{DS} =10V,		22		nS
t _{d(off)}	Turn-Off Delay Time	$R_L=0.5\Omega, R_{GEN}=3\Omega$		40		nS
t _f	Turn-Off Fall Time			25		nS
Qg	Total Gate Charge			22		nC
Q_{gs}	Gate-Source Charge	V _{GS} =4.5V, V _{DS} =10V, I _D =20A		4		nC
Q_{gd}	Gate-Drain Charge			7		nC
Source-Drain D	Diode Characteristics					
I _{SD}	Source-Drain Current (Body Diode)				64	А
V _{SD}	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =20A			1.2	V
t _{rr}	Reverse Recovery Time	l⊧=20A, dl/dt=100A/μs		8		ns
Qrr	Reverse Recovery Charge	l⊧=20A, dl/dt=100A/μs		3		nC

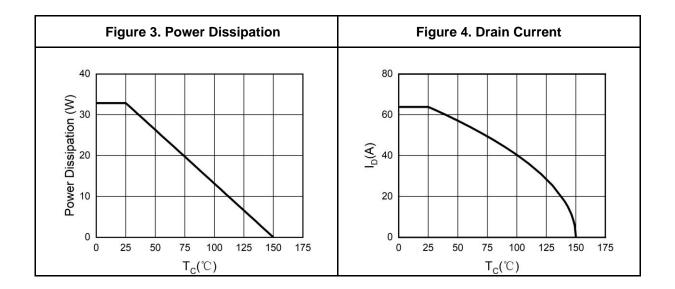
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

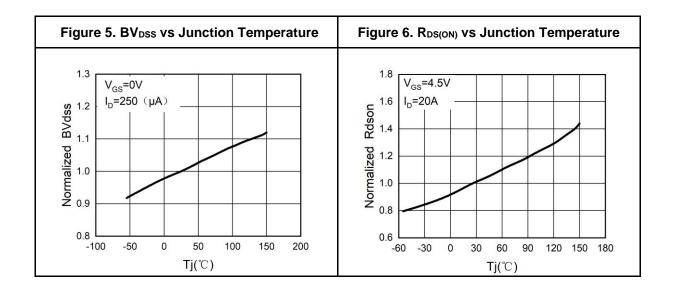
Notes 2.E_{AS} condition: $T_J=25^{\circ}C$, $V_{DD}=20V$, $V_G=10V$, $Rg=25\Omega$, L=0.5mH.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

Typical Electrical And Thermal Characteristics (Curves)

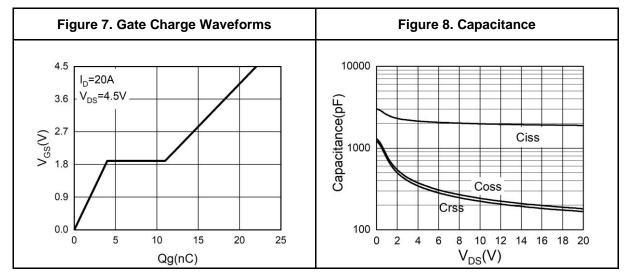


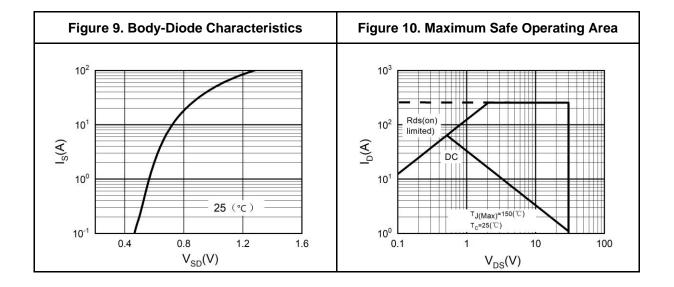






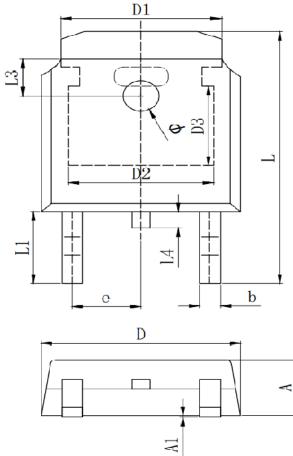
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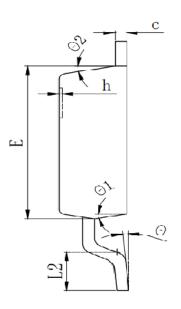






TO-252 Package Information





Symbol	Dimensions In Millimeters			
Symbol	Min.	Тур.	Max.	
А	2.200	2.300	2.400	
A1	0.000		0.127	
b	0.640	0.690	0.740	
c(电镀后)	0.460	0.520	0.580	
D	6.500	6.600	6.700	
D1		5.334 REF		
D2		4.826 REF		
D3	3.166 REF			
E	6.000	6.100	6.200	
е		2.286 TYP		
h	0.000	0.100	0.200	
L	9.900	10.100	10.300	
L1		2.888 REF		
L2	1.400	1.550	1.700	
L3		1.600 REF		
L4	0.600	0.800	1.000	
Φ	1.100	1.200	1.300	
θ	0°		8°	
θ1	9° TYP			
θ2		9° TYP		

Wuxi Shangjia Semiconductor Co., Ltd



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